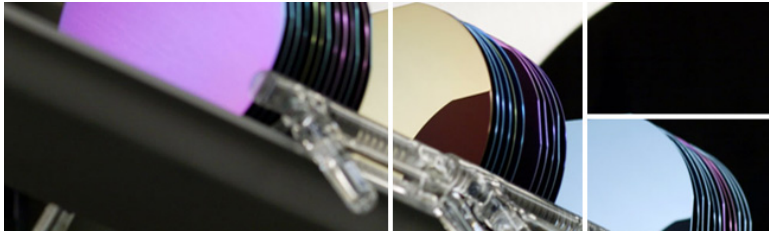




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FPGA Design with Double-Gate Carbon Nanotube Transistors

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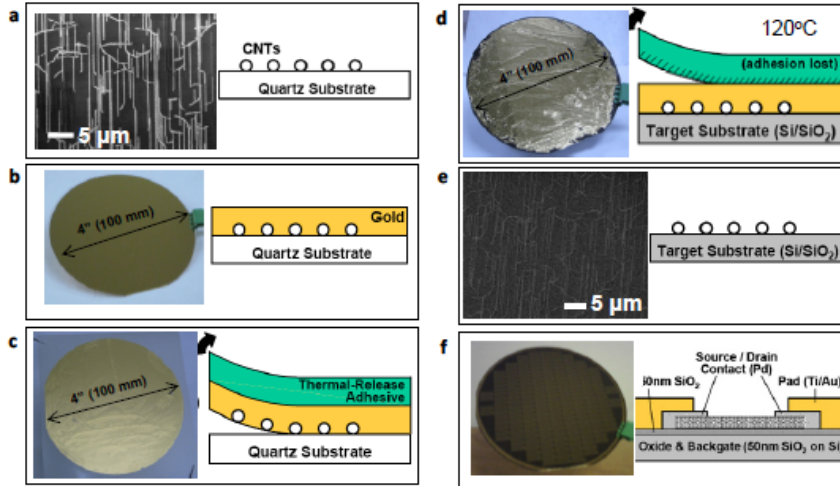
^c Institut des Nanotechnologies de Lyon (INL), Ecully, France

Seminar – Integrated Systems Centre
October 20th, 2011 – EPFL, Switzerland

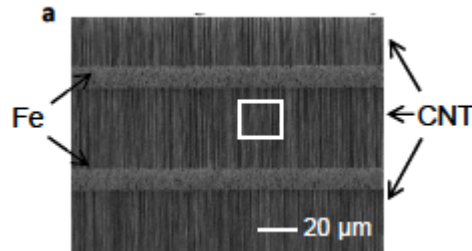
Outline

- Introduction
- Technology and Modeling of DG-CNTFETs
- Fine-Grain Reconfigurable Architecture
- Simulation Results
- Conclusions

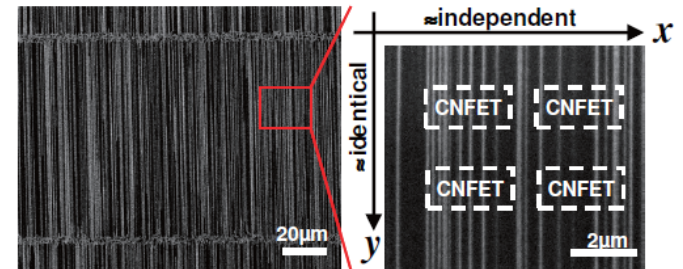
Large Scale Directional Carbon Nanotubes



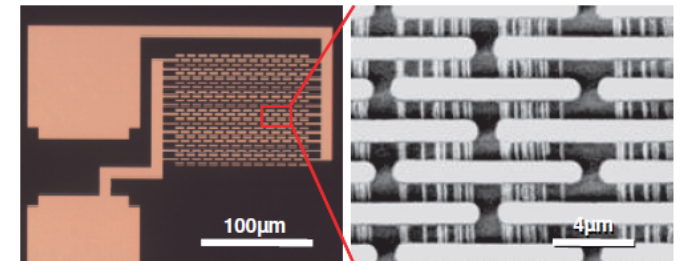
Large scale CNT technology



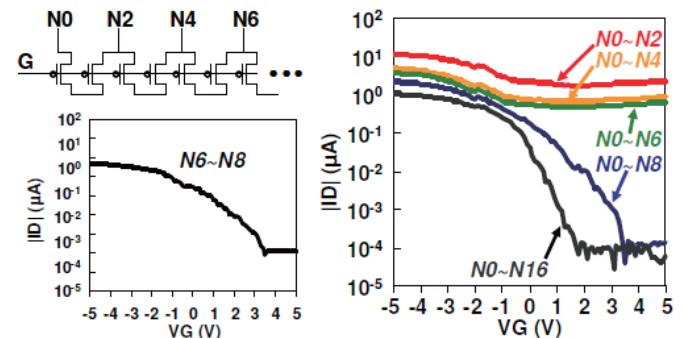
Large scale directional CNT transfer



Asymmetrical Correlation of CNTs



Metallic-CNT-aware CNTFET technique



Fault tolerance of large scale CNTFETs

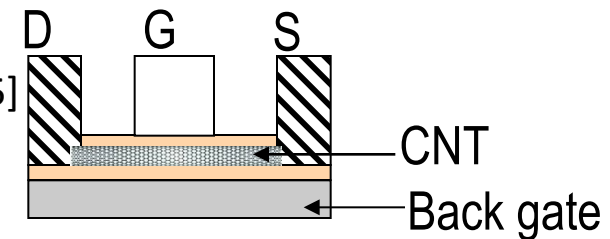
A. Lin et al., Sym. VLSI Tech. '09

N. Patil et al., Sym. VLSI Tech. '08

Ambipolar CNT Technology

- Ambipolar behavior reported on CNTFETs:
 - Conduction under both low and high gate voltage
- Technology demonstration with:
 - Undoped channel
 - Mid-gap D/S contact metal

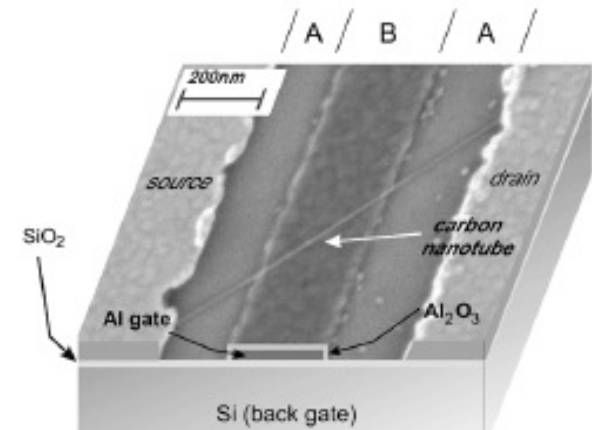
- Polarity control with a double gate:
 - Double gate ambipolar CNTFET [Lin et al., TNANO'05]
 - P-type if low bias on back gate
 - N-type if high bias on back gate



- Ultimate goal:
 - Leveraging electrical benefits of CNTFETs: energy-delay-product (EDP) of CNTFET: 13x better vs. CMOS [Deng et al, ISSCC'07]
 - Controlling device operation (n- or p-type) during circuit operation

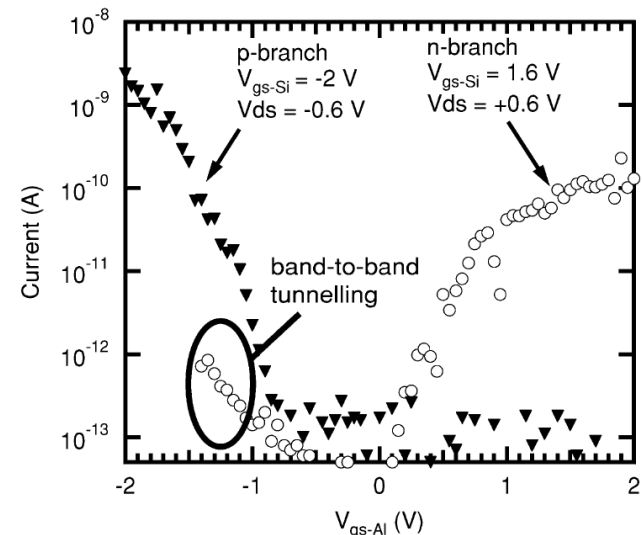
Fabrication of Ambipolar CNTFETs (1/2)

Demonstration of polarity tuning of double-gate carbon nanotube transistors (DG-CNTFET)



Y.-M. Lin et al., TNANO '05

V_{fg}	V_{bg}	state
+V	+V	on (n)
-V	+V	off (n)
+V	-V	off (p)
-V	-V	on (p)
X	0	off (n/p)

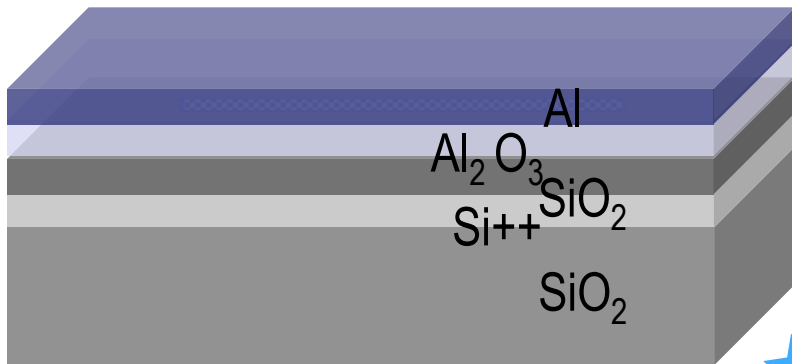
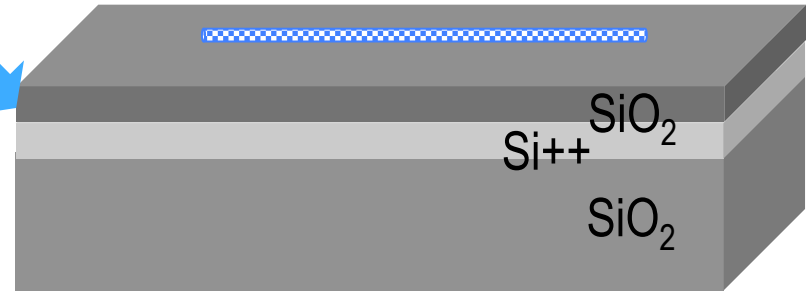


Fabrication of Ambipolar CNTFETs (2/2)



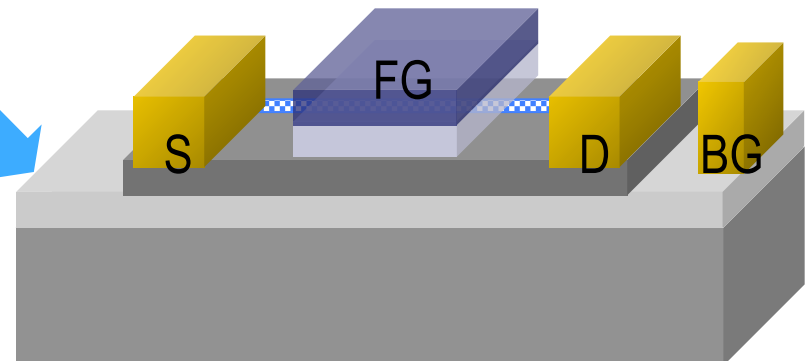
SOI substrate (only BOX and Si visible)
P++ doping of Si
Dry Si oxidation (top SiO₂)

CNT deposition or transfer

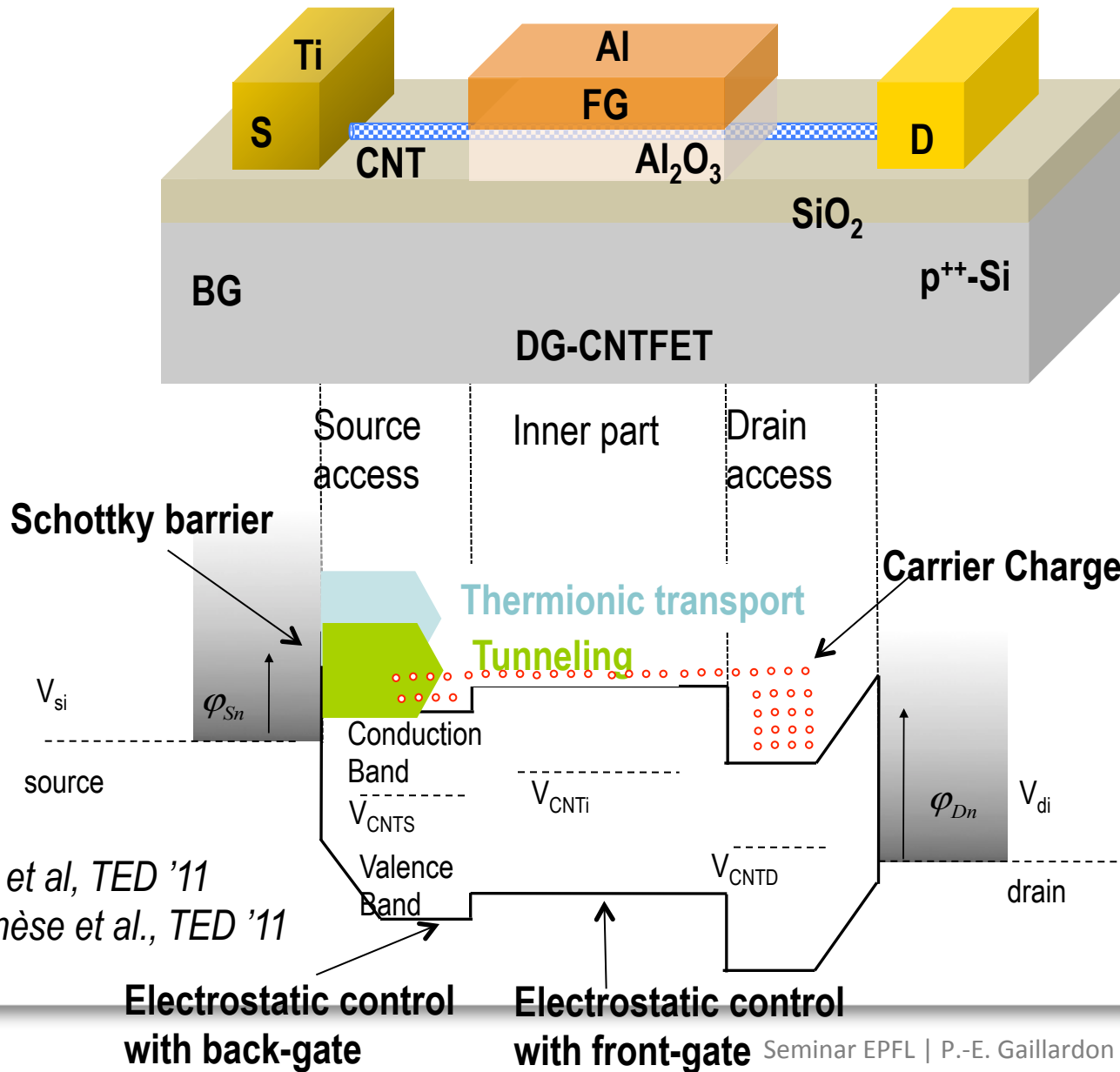


Al₂O₃ (or HfO₂) sputtering
Al sputtering (top gate)

Gate etch
Eventually SiO₂ etch (via opening)
Metallization (eventually different metals)

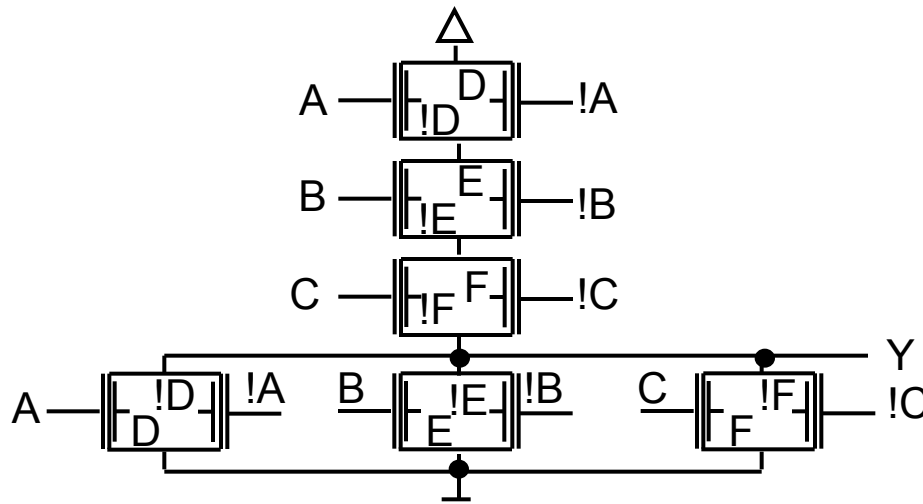


Double-Gate Channel Control



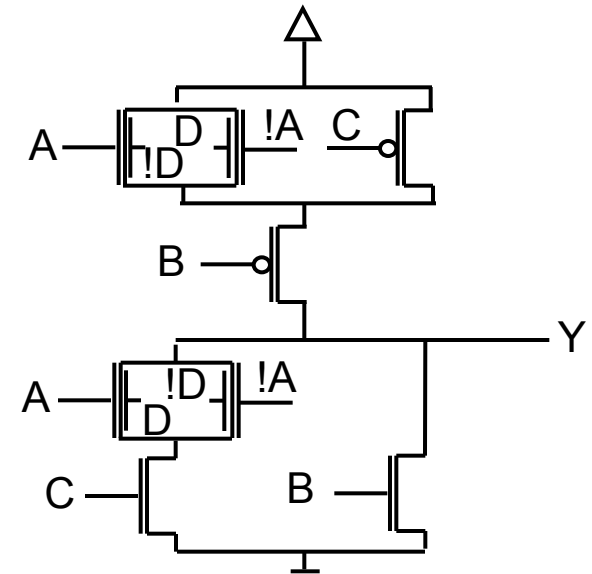
M. Najari et al, TED '11
 S. Frégonèse et al., TED '11

Design of Static Ambipolar Logic Gates



$$Y = \overline{A \oplus D + B \oplus E + C \oplus F}$$

GNAND-style structure



$$Y = \overline{(A \oplus D + B) \cdot C}$$

GAOI-style structure

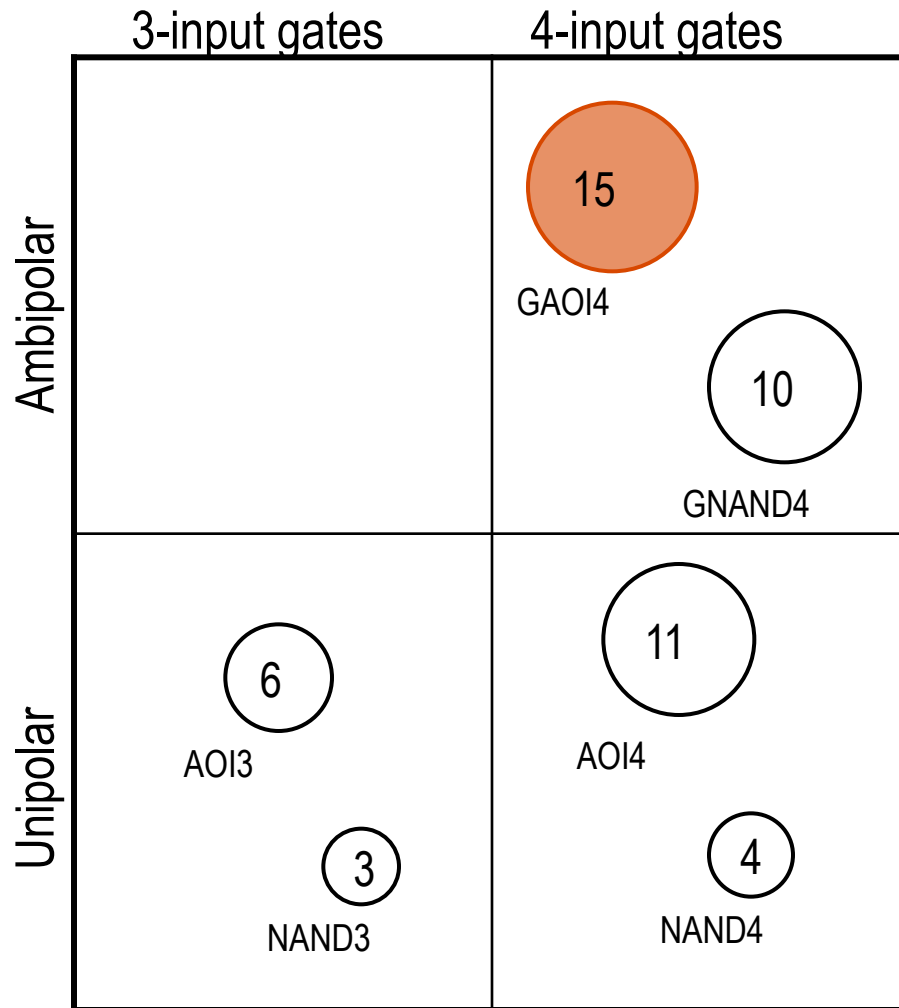
De Marchi et al., Nanoarch '10

Ben Jamaa et al., DATE '09

High Configurability of Ambipolar Logic Gates

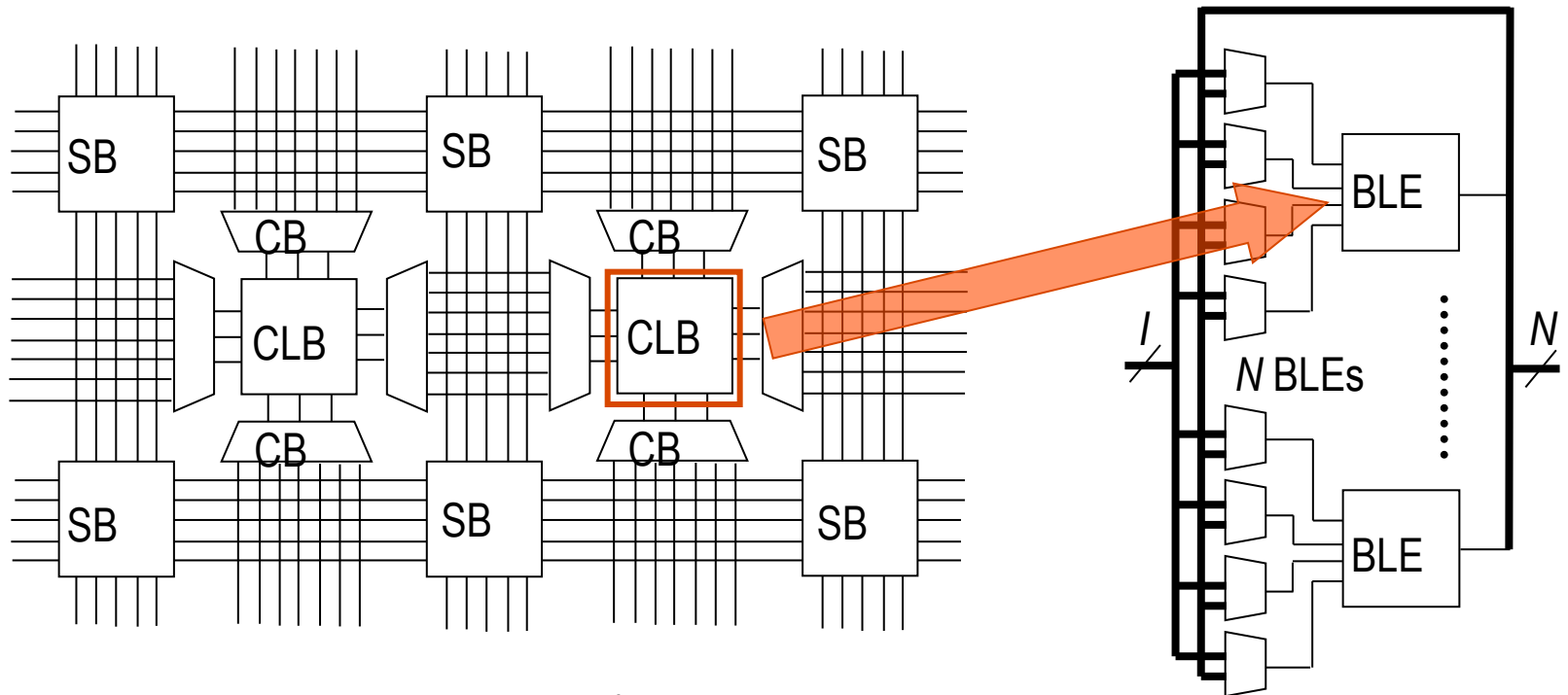
$\neg A$
A
$\neg A + A \cdot \neg B$
$(\neg A) \cdot \neg B + A$
$(\neg A) \cdot \neg B$
$A \cdot \neg B$
$(\neg A) \cdot \neg B + A \cdot B$
$(\neg A) \cdot \neg C + A \cdot \neg B + A \cdot B \cdot \neg C$
$(\neg A) \cdot \neg B + (\neg A) \cdot B \cdot \neg C + A \cdot \neg B$
$(\neg A) \cdot \neg B + (\neg A) \cdot B \cdot \neg C + A \cdot \neg B \cdot \neg C + A \cdot B$
$(\neg A) \cdot \neg B \cdot \neg C + A \cdot B \cdot \neg C$
$(\neg A) \cdot \neg C + A \cdot \neg B \cdot \neg C$
$(\neg A) \cdot \neg B \cdot \neg C + A \cdot \neg B$
$(\neg A) \cdot \neg B \cdot \neg C + (\neg A) \cdot \neg B \cdot C \cdot \neg D + (\neg A) \cdot B \cdot \neg D + A \cdot \neg B \cdot \neg D + A \cdot B \cdot \neg C + A \cdot B \cdot C \cdot \neg D$
$(\neg A) \cdot \neg B \cdot \neg D + (\neg A) \cdot B \cdot \neg C \cdot \neg D + A \cdot \neg B \cdot \neg C \cdot \neg D + A \cdot B \cdot \neg D$

Functionality of GAOI4



Benchmark of functionalities

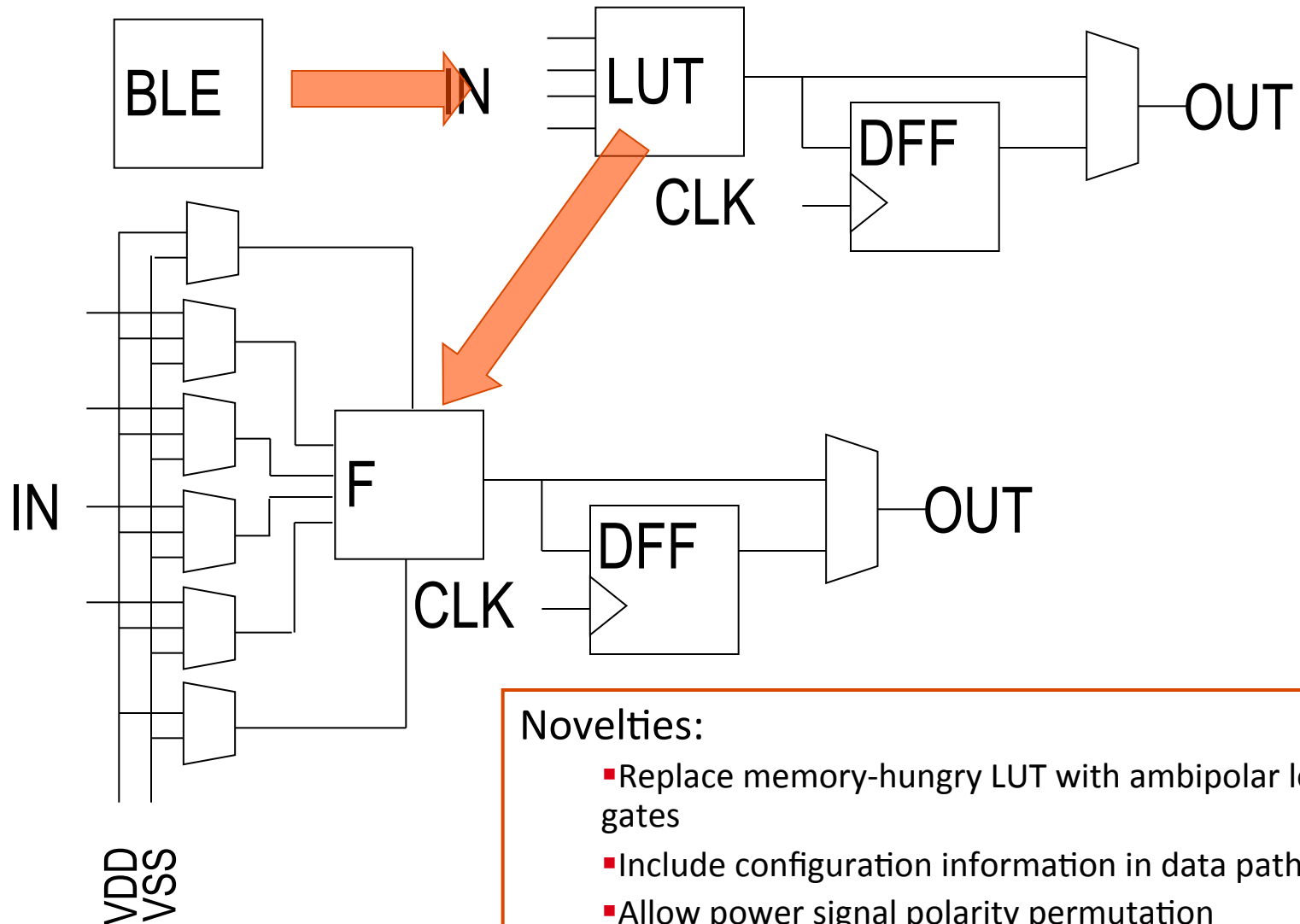
Reconfigurable FPGA Architecture



- CLB: complex logic block (logic macro-cell) with I inputs and N outputs
- CB: connection block (routing)
- SB: switch block (routing)
- BLE: basic logic element

V. Betz et al., "Architecture and CAD for Deep-Submicron FPGAs", Kluwer Academic Publishers '99

Enhanced FPGA Architecture

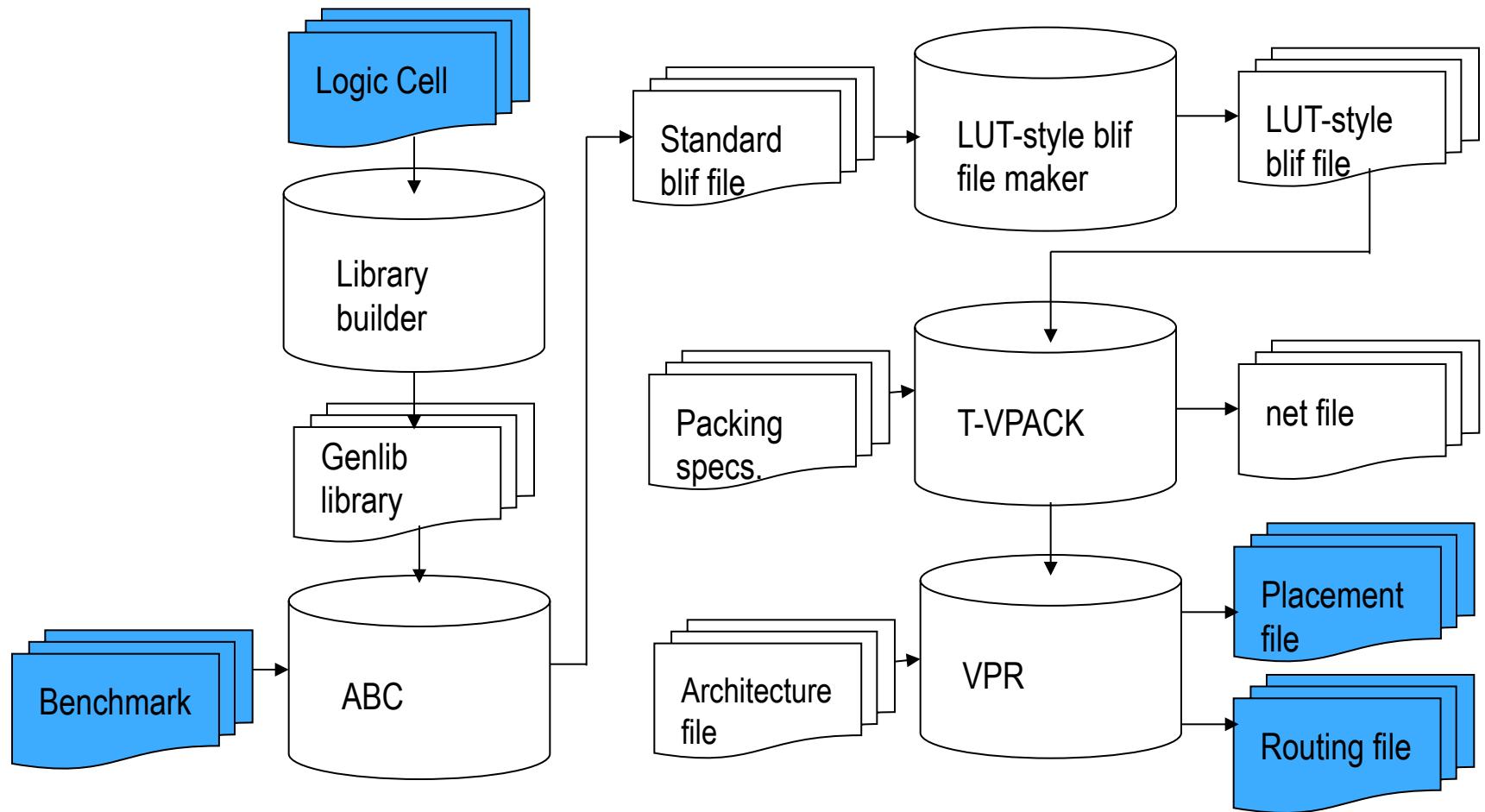


Simulation Scenarios

Scenario	Logic type	N	I	Norm. CLB area	Intra-CLB delay (ps)	Inter-CLB delay (ps)
S1	Reconf. ambipolar gates	1	4	2419	47	25
S2	LUT	1	4	2560	50	25
S3	Reconf. ambipolar gates	10	22	17167	200	423

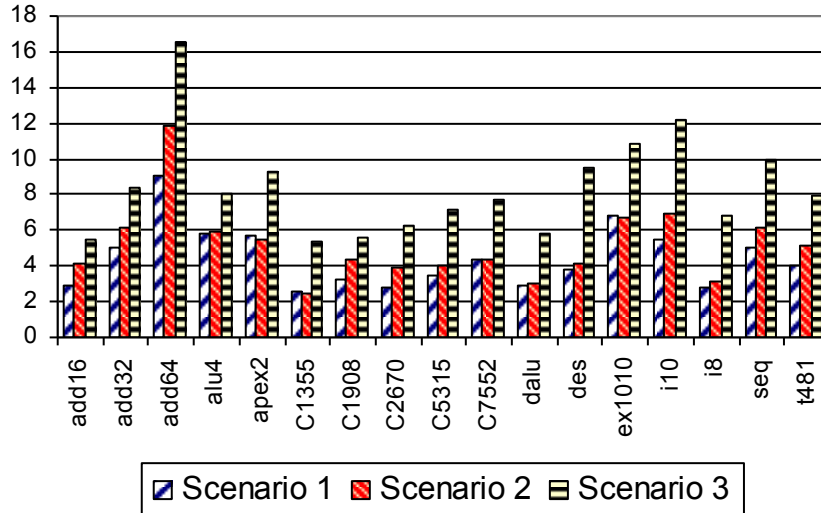
- Fine-grain architectures have smaller area- and intra-CLB delay.
- They have a lower inter-CLB delay because of lower load on CLB in- and outputs.
- Gate-based architectures are more compact because of a lower need for memory and the compact gate design.

Synthesis Flow

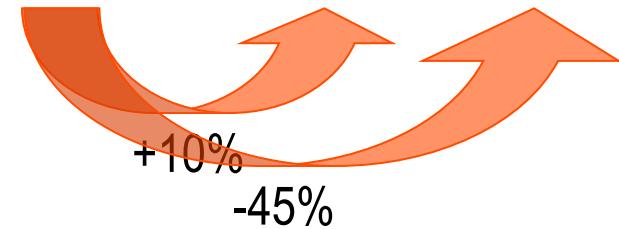
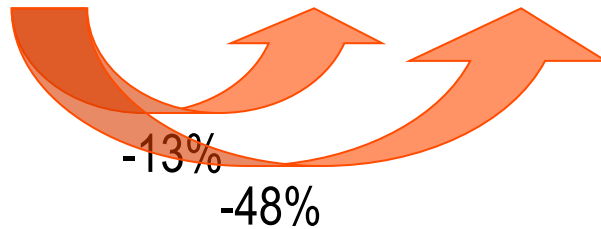
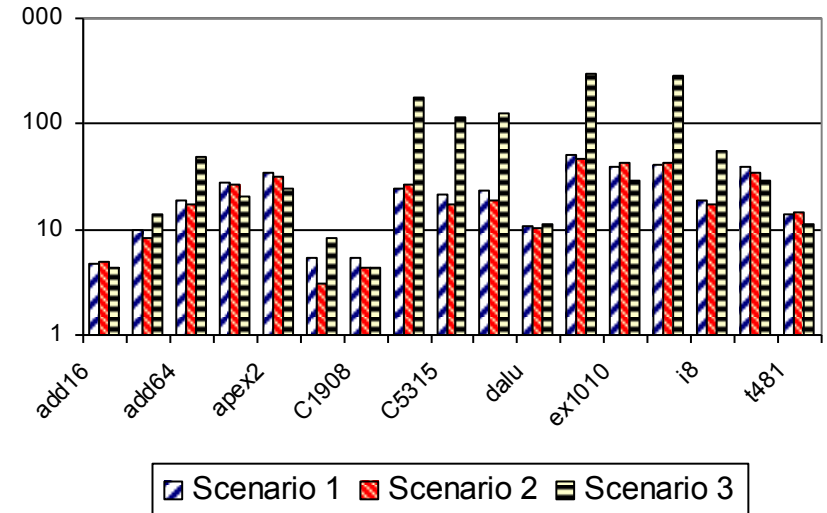


Simulation Results

Delay (ns)



Normalized area (million unit area)

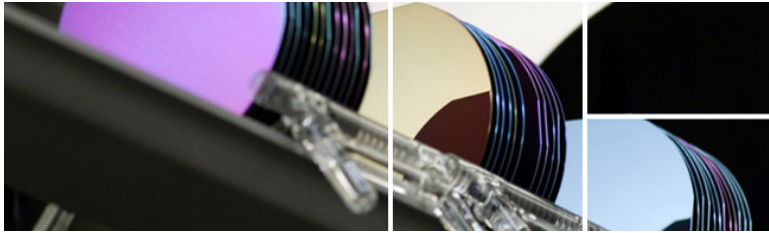


Conclusions

- Double-gate carbon nanotubes FETs offer the opportunity to tune the device polarity.
- Reconfigurable FETs can be used in fine-grain reconfigurable logic circuits, such as FPGAs.
- These devices have a higher functionality that we leveraged in FPGAs design:
 - Compact logic, polarity permutation, configuration through the data path
- The approach offers faster FPGAs especially for fine-grain systems



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Thank you for your attention

Questions ?

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